# Introduction to the Design of Full-Custom Front-End & Data Transmission ASICs\*

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### The Big (but Brief) Picture

- Briefly front-end FE ASICs
- → Briefly read-out RO systems
- → Briefly serializer SER
- → Briefly phase-lock loop PLL

### Feed-Back Concept

- → A qualitative introduction
- Natural frequency concept ω<sub>n</sub>
- → Real-world examples:
  - **→ Binary** read-out
  - → Time-over threshold
- Adjusting/optimizing loop behavior
  - → Damping ratio §

#### Detector Front-End ASICs

- → Pre-Amplifier: basic idea V<sub>out</sub> / V<sub>in</sub>
- → Transconductance of a transistor g<sub>m</sub>
- Evolving a single-stage amplifier into a real-world application

### Processing Technology

- → Transistor switch A masterpiece
  - Lithography
  - Formation of an nMOS transistor
- VLSI design flow
  - Parasitic extraction
- Real-world ASIC examples

#### Radiation Tolerance Issues

- Definitions:
  - Single event upset, analog single event transient, latch-up
- Simulating radiation effects on analog circuits

### Potential CMOS Replacements(?)

- Single-layer thick transistors
  - Graphen'ics (benzen lattice)
  - → Molybdenite'ics (MoS<sub>2</sub>)

\* Application Specific Integrated Circuit

### Motivation for the TOC

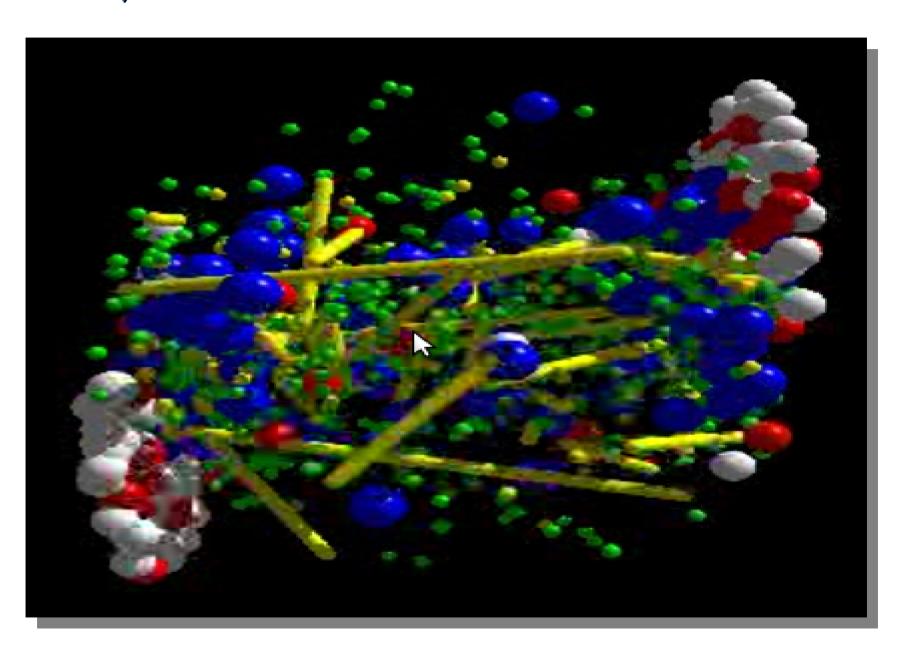
Composition within the ISOTDAQ curriculum

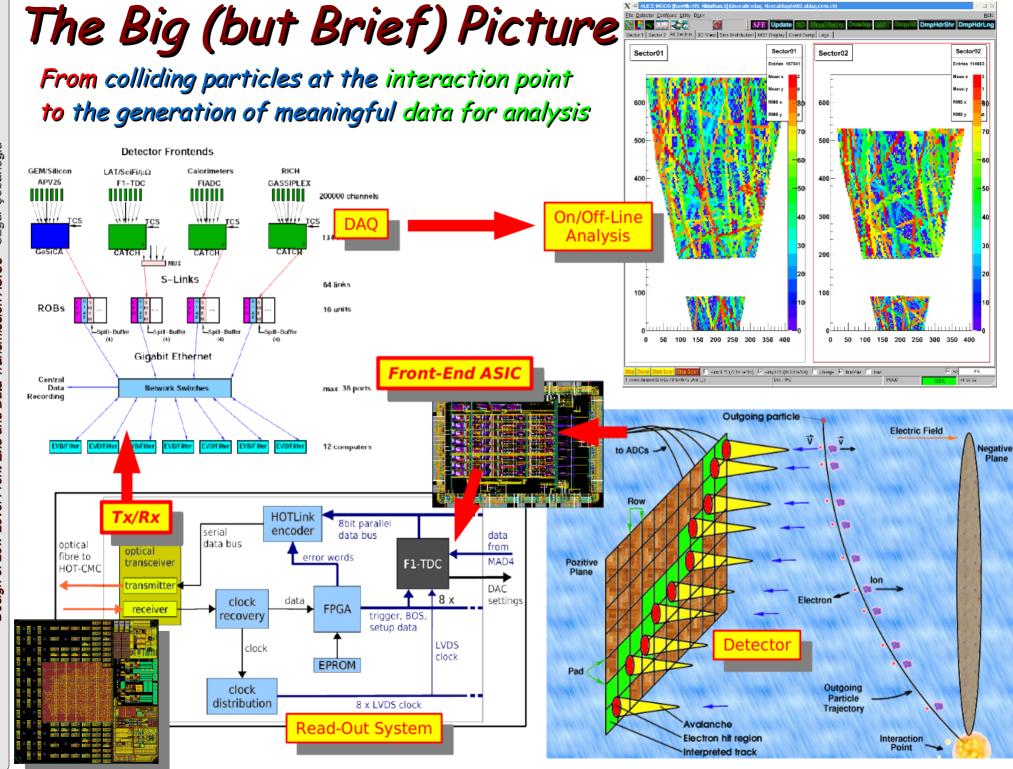
- One of the official goals of the school is to "expose the participants to a maximum variety of topics"
- What comes just after the "detector" is the first link of the DAQ chain
- Therefore this lecture will try to deliver:
  - → an intuitive approach to what is listed in the TOC
  - → without providing "dry and ugly" math phrases
- This lecture will have no specific hands-on laboratory session in the current program of the school
  - → However it will **always** be there at the lowest level of all the laboratory sessions you will attend
- The pages will contain enough amount of text necessary for you NOT to need a lecturer in order to understand the slides at home (naively assuming that you will refer to this lecture in near future)
  - → Therefore please be aware of the above fact, in case you start feeling that the pages are a little bit overloaded

## An Ordinary Heavy Ion Collusion Heavy ions at the center of ALICE detector; a short movie of 5 ns



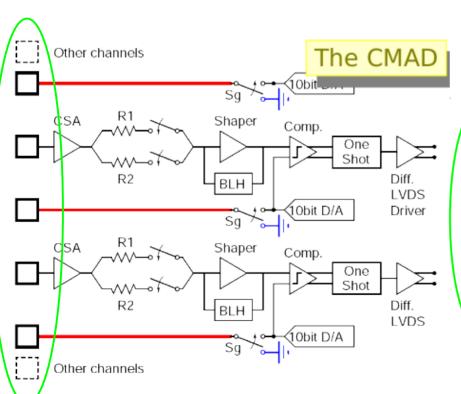
## An Ordinary Heavy Ion Collusion Heavy ions at the center of ALICE detector; a short movie of 5 ns

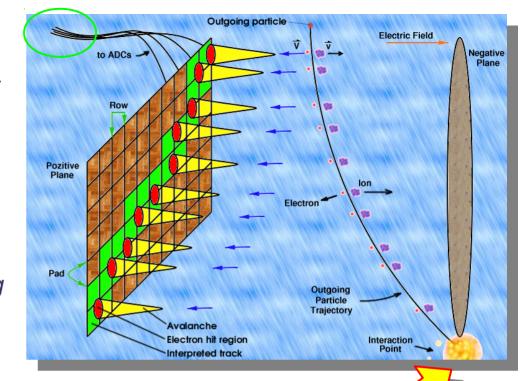


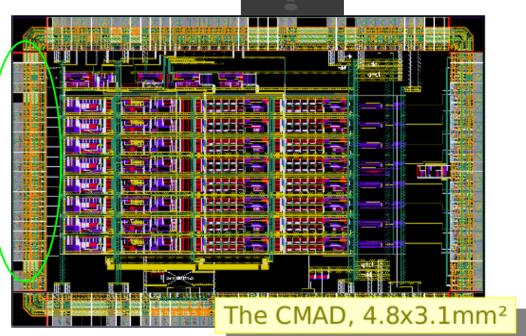


## Briefly Front-End First interpretation of detector data

- Integrate the charge as a pulse
- Shape this pulse
- 1) Compare pulse height to a threshold
  - Higher ? Yes : No
- 2) Digitize the pulse for further processing
  - → Digital filters, corrections, etc.
- Send the result to read-out

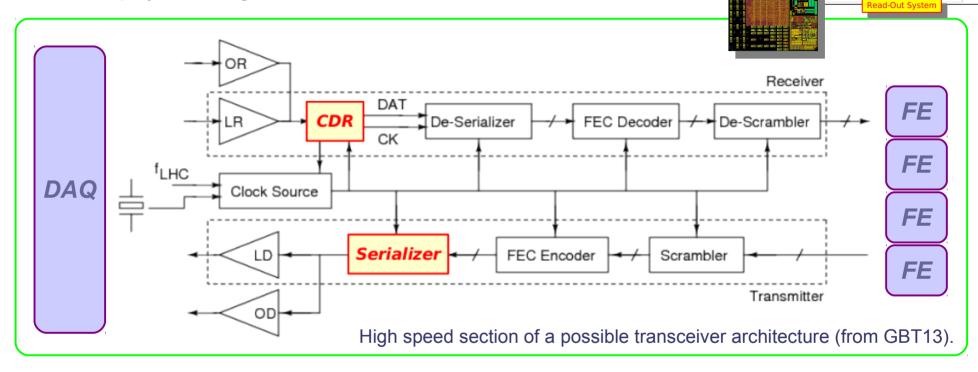






## Briefly Read-Out How to get data from FE and deliver to DAQ

- Add header / trailer to the data created by the detector FEs
- Combine payload fragments into frames to be transmitted to DAQ



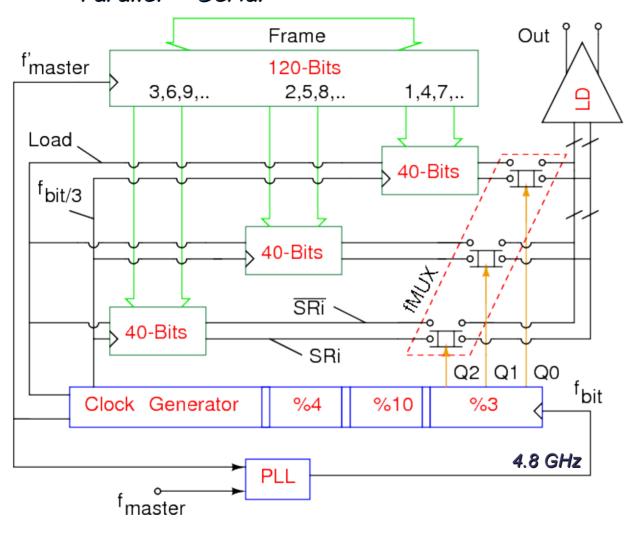
#### Receiver

- → Receive laser light representing serial data from fiber
- Check **FEC** code and **correct** errors (if possible)
- Parallelize data
- → **Deliver** data to the next stage e.g. FE

#### Transmitter:

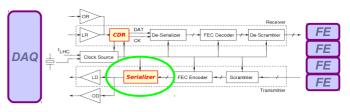
- Get data from FE
- Calculate FEC and add to frame, increasing resistance against transmission errors
- → Serialize parallel data
- → Drive a laser diode over fiber to DAQ

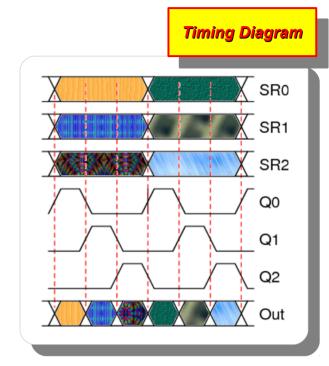
## Briefly SER Parallel -> Serial

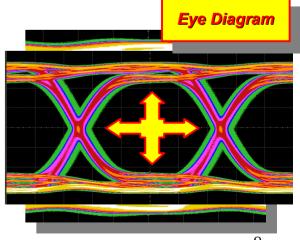


#### Operation:

- @ rising edge of f<sub>MASTER</sub>, load 120-bit-wide frame into input register (40 MHz)
- @ rising edge of Load, divide the frame into 3 40-bit-wide words (40 MHz)
- rising edge of f<sub>BIT/3</sub>, right shift 30-bit-wide words sequentially (1.6 GHz)
- After every shifting, multiplex the right bit to output (4.8 GHz)

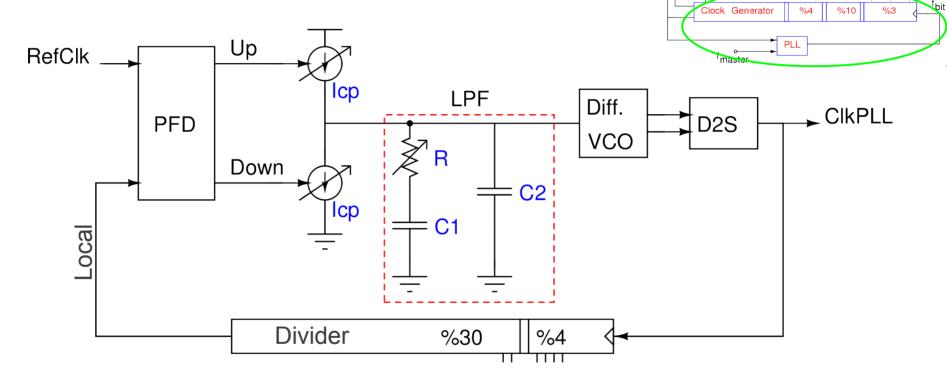






## Briefly PLL Phase-lock loop

- Locking a clock to a (pseudo) periodic signal
- CIKPLL is what we we generate locally and RefClk is the reference to be tracked or to be locked to



- Measure the rising instant timing difference between RefClk and ClkPLL by the phase-frequency detector (PFD)
  - Generate correction commands depending on this measurement (Up, Down)
- Correction commands control the charge pump (Icp) pumping/sinking current into/from the filter capacitor, varying the control voltage for the Voltage Controlled Oscillator (VCO)
  - Gradually, the timing error of the two signals at the inputs of the PFD would vanish (ideal locked condition)

Frame

40-Bits

120-Bits

2,5,8,..

1.4.7.

t'<sub>master</sub>

Load f<sub>bit/3</sub> 3.6.9...

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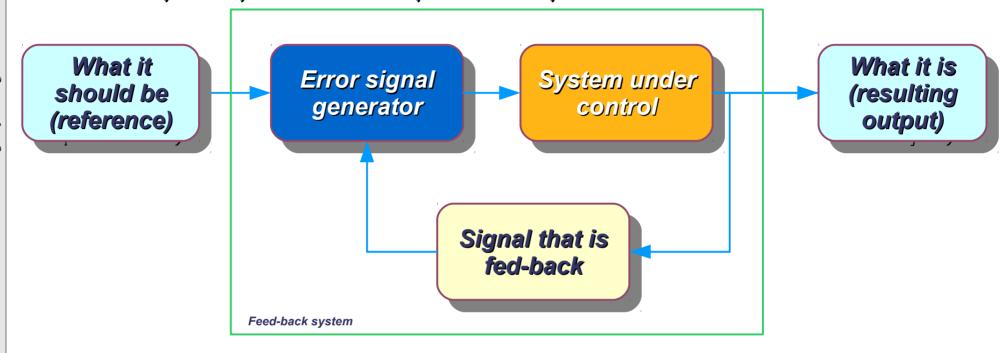
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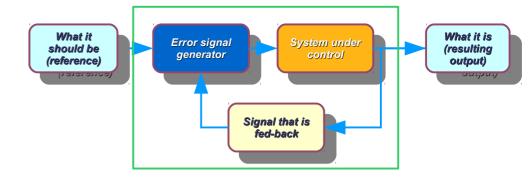
### Feed-Back

Actually a very familiar concept from daily life



- Aim, is decreasing the difference (the error signal) between the reference and the output
- How ? For each cycle:
  - → A **portion of the output** is fed-back. Make the system be **sensitive** to a portion of what it outputs
  - Measure the difference between the reference and what is fed-back (only a portion of the output)
  - Depending on the difference, an error signal is generated which in turn causes a correction step to be taken controlling the system under control
  - Repeat the cycle

# Feed-Back Actually a very familiar concept from daily life



- Whistling or playing an instrument ?
  - → How do I know what I play is a "Do" but not a "Re"?
  - → Does it make sense to say "I whistle better than you"?
  - → What happens when I try to find the right guitar solo for an existing song?
- Drinking a glass of water ?
  - Adjust the angle & position of the glass accordingly to keep the water flow as it is necessary?
  - → Remember the childhood: sometimes the water gets dropped to the ground accidentally (What is the **failure mechanism**?)
- Walking and biking ?
  - → How do I decide the frequency of my steps not to fall down or to be able to reach somewhere?
  - What about walking or biking when drunk? (What is the failure mechanism?)
- Ruling a country ?
  - → Can "referendum" be a term borrowed from the control theory?
  - → How come politicians of the same ideology can decide in substantially different manners? < Questionably ignoring corruption :D >

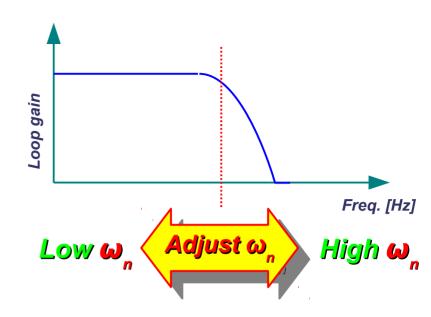
#### Feed-Back What it What it is System under should be (resulting generator control (reference) output) Natural frequency concept Signal that is fed-back Corner 100% Correct answers [%] Success $T(s) = \frac{\omega_n^2(\tau s + 1)}{\frac{s^2}{N} + 2\xi s \frac{\omega_n}{N} + \frac{\omega_n^2}{N}}$ Decreasing success How frequent the questions are asked [Hz] ω

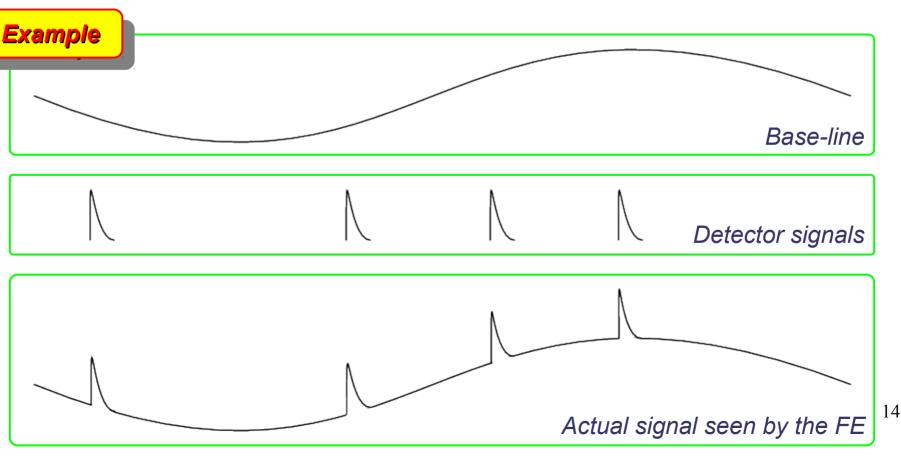
- An imaginary system answering questions asked continuously
- Plot (both logarithmic scale) the success level within a certain time window as a function of frequency of questions asked (transfer function)
- If the questions are asked slow enough, the system answers all, thus 100% success level
- Once the questions start to be asked faster, the system starts failing answering all, thus transfer function begins going down
- Corner is at the natural frequency of the control loop where the system starts impairing significantly

### Feed-Back

Choosing for what to be sensitive

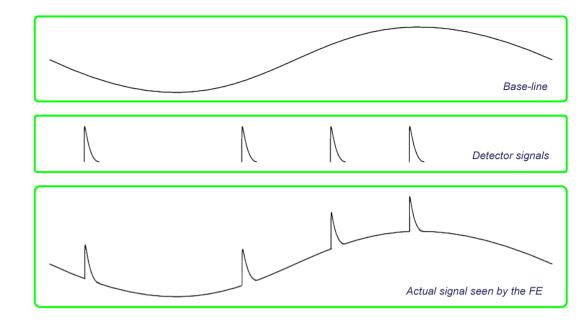
- Low ω<sub>n</sub> → Sense slow variations
  - → Loop acts on slowly varying signals
  - → Narrow bandwidth slow loop
- High ω<sub>n</sub> → Sense fast variations
  - → Loop acts on rapidly varying signals
  - → Wide bandwidth fast loop

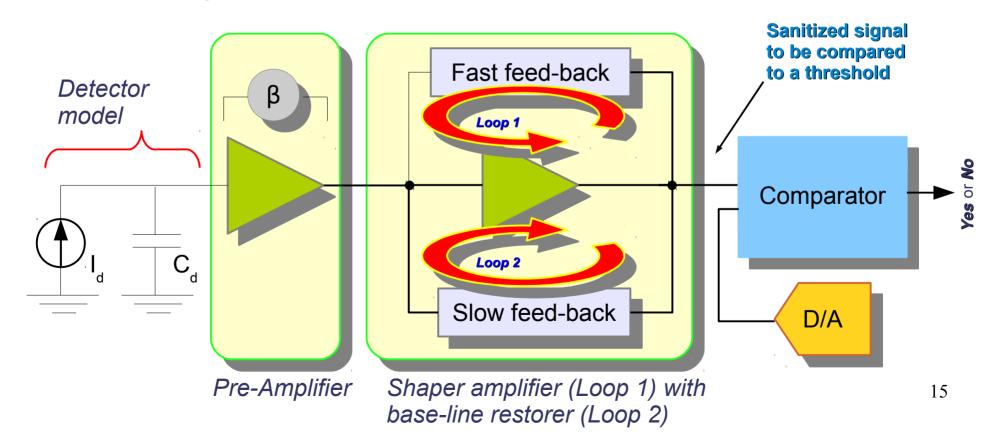




### Example Binary read-out

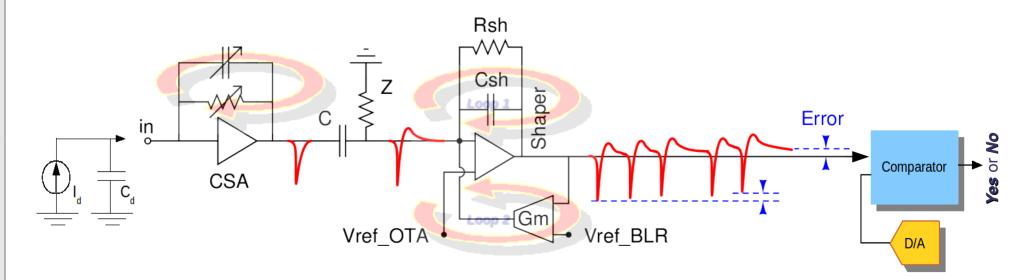
- Requires stable base-line
  - Which varies slowly
  - → A narrow loop bandwidth is needed (Loop 2)
- Requires a fast signal shaper
  - Which varies rapidly
  - → A wide bandwidth is needed (Loop 1)

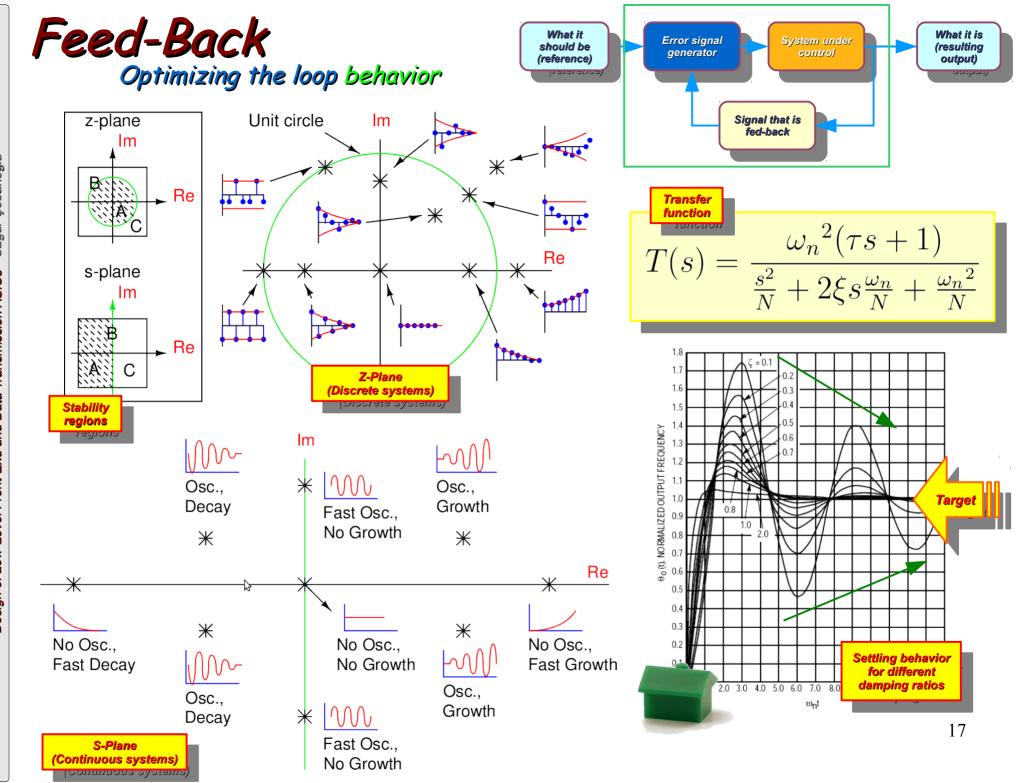




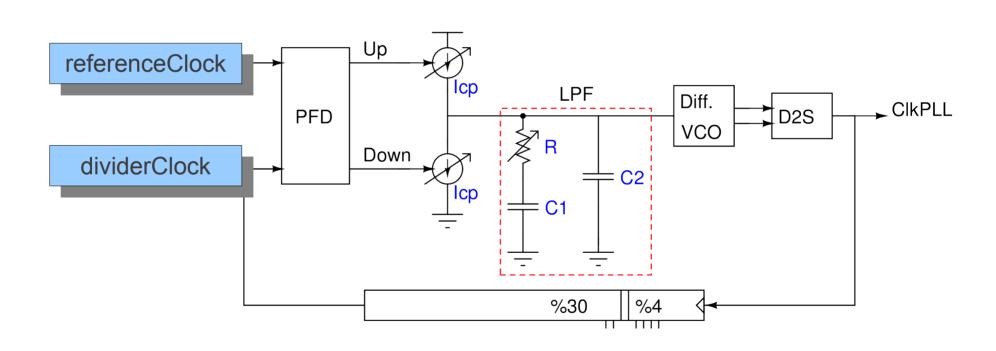
### Real-World Example Binary read-out for time-over threshold measurement

- **Random** detector **pulses** with a few MHz frequency; then...
  - How fast is the fast loop?
  - How slow is the slow loop?
- Depending on the read-out **speed** and the operating environment, parameters are optimized
  - → Natural frequencies and gains of the loops, rise/fall-times, etc.
  - Settling behavior, radiation tolerance, damping ratio, power, etc.
  - Circuit footprint, robustness, redundancy, channel efficiency, etc.



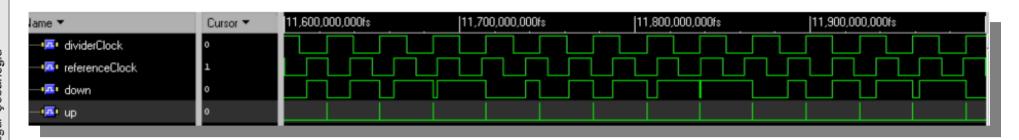


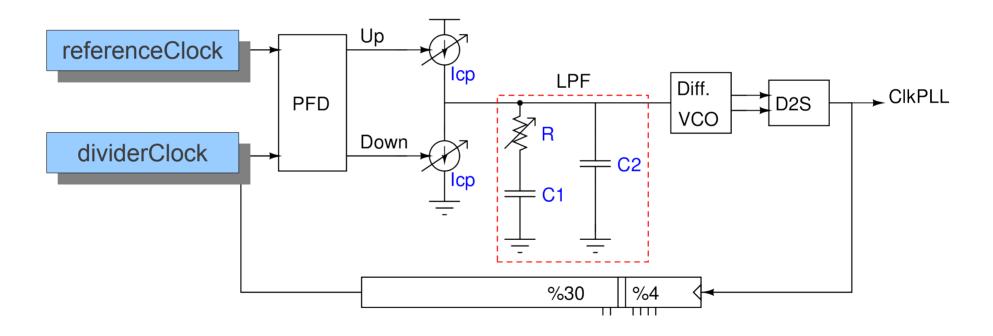
## Simulation Movie Quiz Remember the PLL



- Slow down the VCO, if it is too fast with respect to the reference
- Speed up the VCO, if it is too slow with respect to the reference

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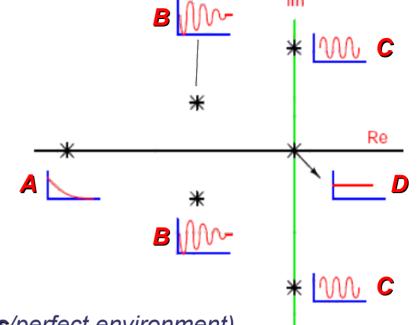




- Slow down the VCO, if it is too fast with respect to the reference
- Speed up the VCO, if it is too slow with respect to the reference

See the movies and associate the behavior to the poles on the s-plane (complex plane)

Use your intuition

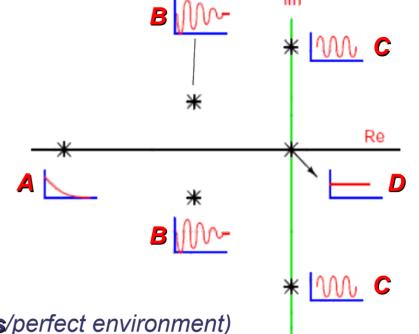


? - Slow-loop with low damping ratio (noiseless/perfect environment)

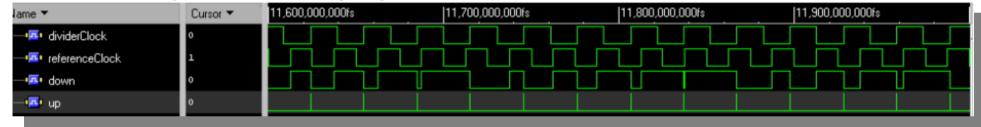
? - Fast-loop with high damping ratio (noiseless environment)

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Use your intuition



? - Slow-loop with low damping ratio (noiseless/perfect environment)

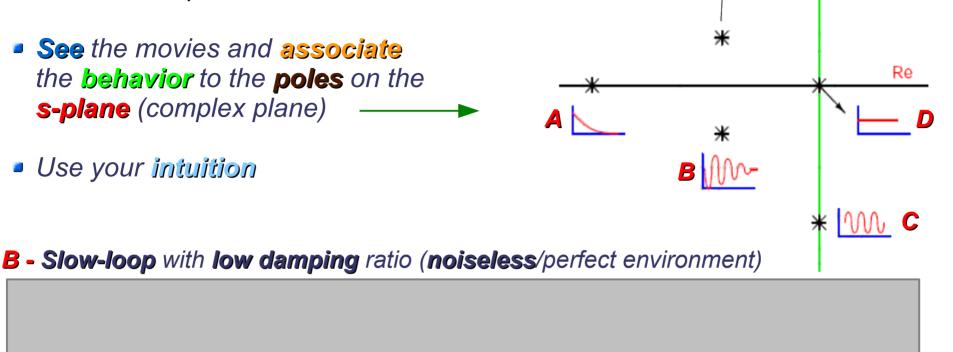


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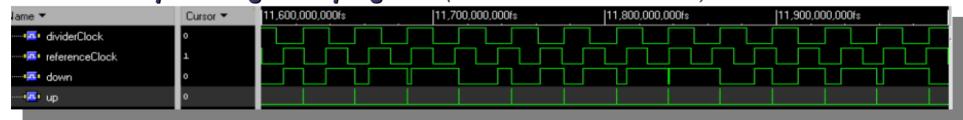
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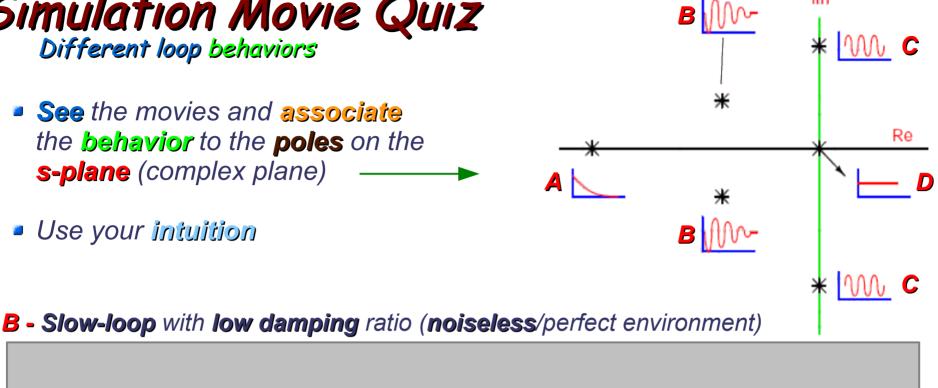
**B - Slow-loop** with **low damping** ratio (**noiseless**/perfect environment)

? - Fast-loop with high damping ratio (noiseless environment)



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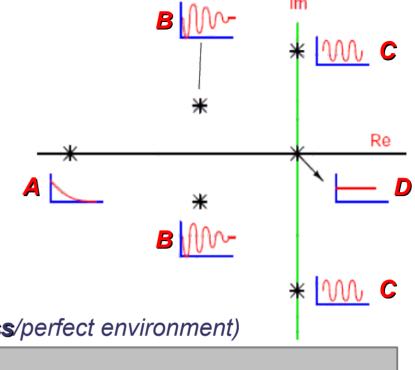
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A - Fast-loop with high damping ratio (noiseless environment)

See the movies and associate the behavior to the poles on the s-plane (complex plane)

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B - Slow-loop with low damping ratio (noiseless/perfect environment)

A - Fast-loop with high damping ratio (noiseless environment)



### Back to the big picture

If the PLL fails, then nothing works!..

- In case the loop parametrization is wrong:
  - → PLL can not deliver a proper clock
    - No phase/frequency locked ClkPLL signal
    - Ignored LHC clock, no synchronization
  - → SER fails

RefClk

- Some of the bits get lost or duplicated
- → High jitter leading to closed eye diagram

**Icp** 

**LPF** 

R

**C1** 

%30

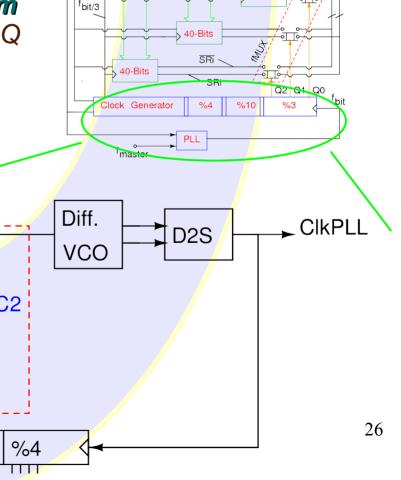
→ RO fails delivering the data from FE to DAQ

Up

Down

No DAQ → Fatal error !...

**PFD** 



120-Bits

2.5.8...

DAQ

r<sub>master</sub>

Load

3.6.9...

FE

FΕ

Out

1,4,7,.

40-Bits

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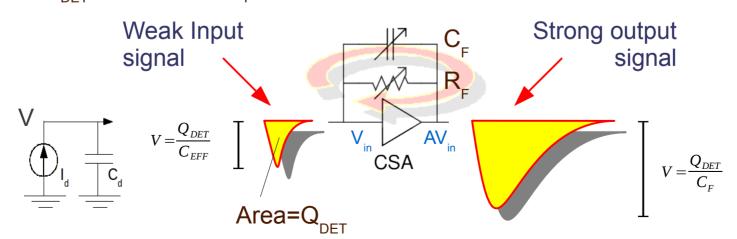
- Single-layer thick transistors
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### Pre-Amplifier The first stope of the inter-

The first stage of the interpretation

- Standardized experimental techniques over time
- Our discussion on intuitive & descriptive level
- $T = \frac{V_{OUT}}{V_{IN}} = \frac{A}{1 + AB}$   $\frac{\text{sage: } T(A, B) = A/(1 + A * B)}{\text{sage: } T.\text{limit}(A = \text{infinity})}}{(A, B) \mid --> 1/B}$

- Three types of pre-amplifiers:
  - → Voltage sensitive: usually not preferred due to the fact that, for a given amount of charge generated by the detector (Q<sub>DET</sub>), the output voltage of the detector (V) is a function of the effective capacitance (C<sub>EEE</sub>) of the detector which is variable
  - Current sensitive: not preferred because they are suitable to be used with low impedance devices, however radiation detectors have usually high impedance
  - → **Charge sensitive**: **preferred** type because its output is **only** a function of the charge (Q<sub>DET</sub>) and a fixed C<sub>F</sub>, provided that amplifier **gain** is sufficiently **high**



out

### Amplifier Basic How to amplify something

We want a small change in the input to cause a big change at the output

→ The **reason** it is called an amplifier

However in a real circuit, the input signal **dies** out, therefore:

Output signal is a re-generated larger "clone"

Output can have other features that the input did not

stick

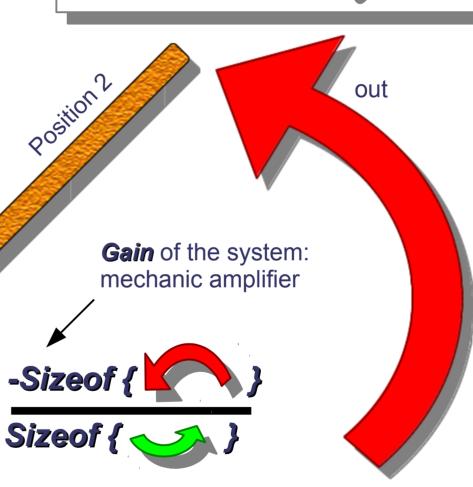
Rotational

support

point

Light-weight

Gain= s



Position 1

CSA

Strong output

signal

Weak

input

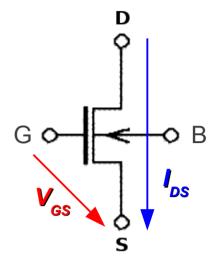
signal

Support (the amplifier)

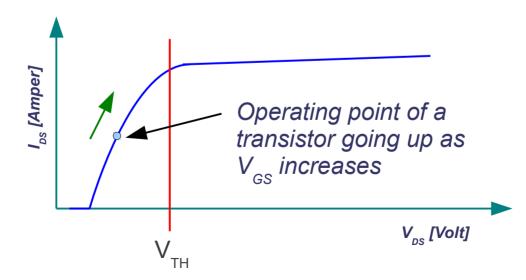
### Transconductance - $g_m$

Figure-or-merit (FOM) for a transistor

- Define a figure-of-merit (FOM) for a single nMOS
  - → How well a transistor converts voltage into current
  - From input V<sub>GS</sub> to output I<sub>DS</sub>



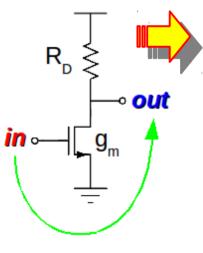
$$g_m = \frac{dI_{DS}}{dV_{GS}} = \frac{2I_D}{V_{GS} - V_{TH}}$$

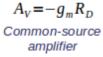


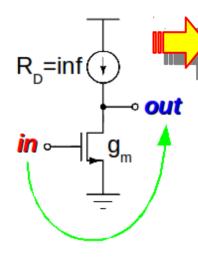
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## Basic CMOS Amplifier Single-stage common-source amplifier and its evolution into a complete circuit

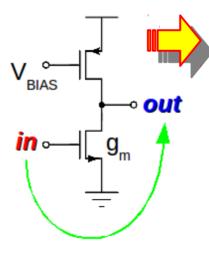
- Sink current through R<sub>n</sub>
  - → As in increases, out decreases (faster)
- -g\_R suggests that we should increase the load impedance to have higher voltage gain
  - An ideal current source has infinite impedance
- A current mirror is a practical current source
  - Simply a transistor biased as a current source
- Transconductance (g\_) increases with current
  - Supply additional current to the gain device to have higher gain



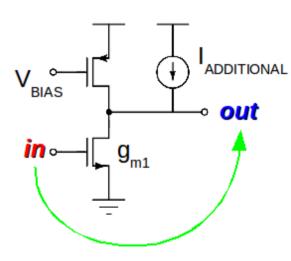




$$A_V = -g_m r_o$$
Common-source
amplifier



 $A_{V} = -g_{m}(r_{o1}||r_{o2})$ Common-source amplifier

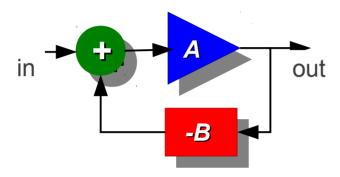


$$A_V > -g_m(r_{o1}||r_{o2})$$

Common-source amplifier with current source load featuring higher gain due to increased current

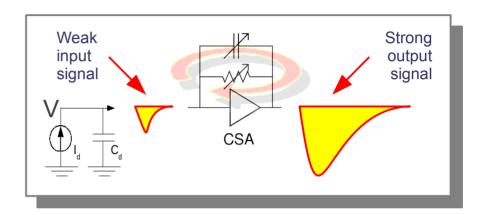
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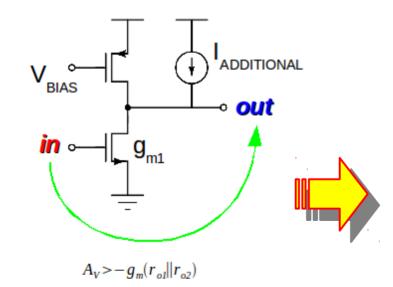
- Add the feedback network C<sub>E</sub> & R<sub>E</sub> forming the B such that
  - For high enough A<sub>v</sub>, closed loop gain is 1/B

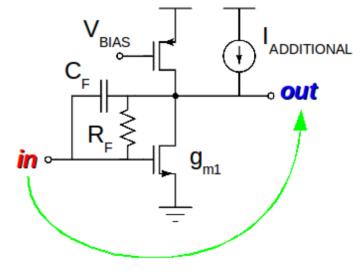


$$T = \frac{V_{OUT}}{V_{IN}} = \frac{A}{1 + AB}$$

$$\begin{array}{c} \text{sage: } T(A, B) = A/(1 + A * B) \\ \text{sage: } T.\text{limit}(A = \text{infinity}) \\ (A, B) \mid --> 1/B \end{array}$$





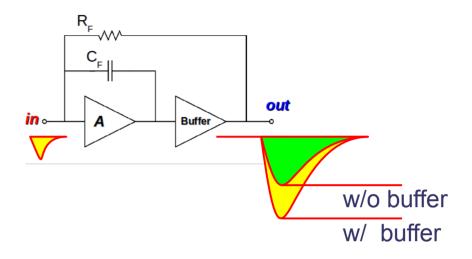


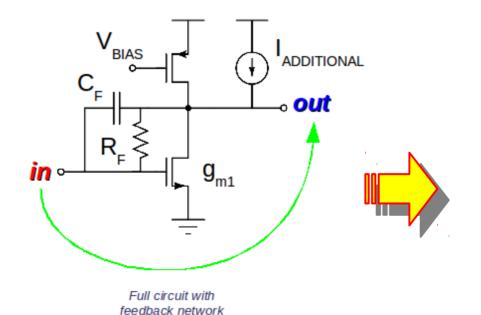
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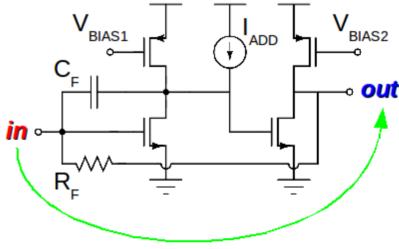
Full circuit with feedback network

## Basic CMOS Amplifier Avoid loading effect of the resetting resistor

- Problem: while c<sub>i</sub> is charged, R<sub>i</sub> resets at the same time
  - **Lowering** the voltage gain, therefore:
  - **→ Loading effect** of the feedback resistor should be avoided
  - → Integration and resetting should be decoupled
  - Employing a buffer is one of the possible solutions





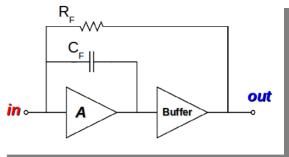


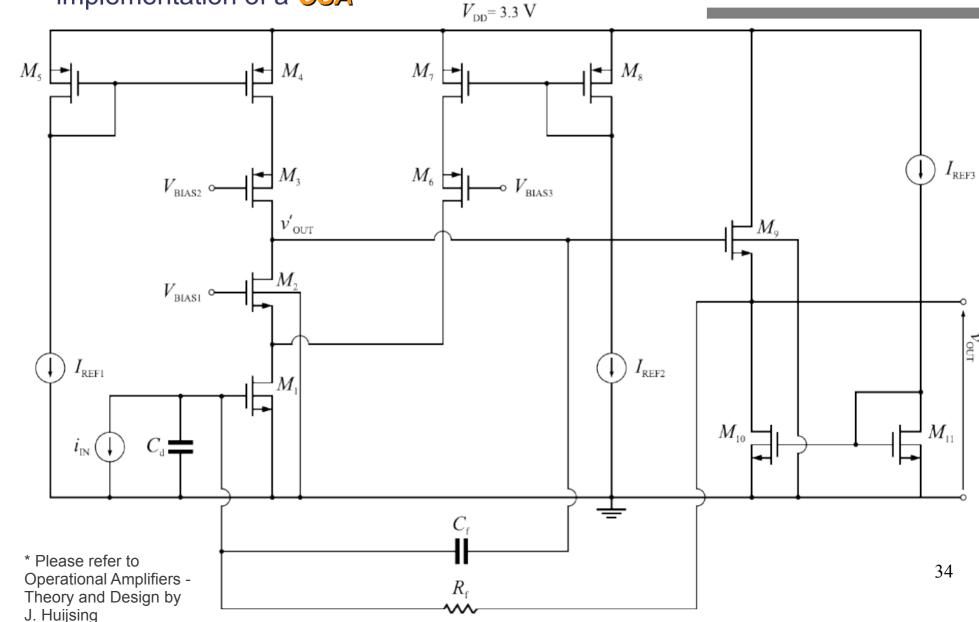
Full circuit avoiding resistor loading effect

### Pre-Amplifier

Full circuit (currently in use at a RICH detector)

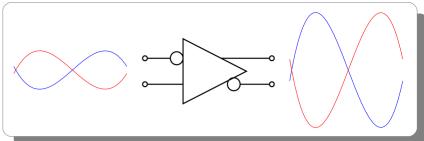
 Actual CMOS device-level implementation of a CSA

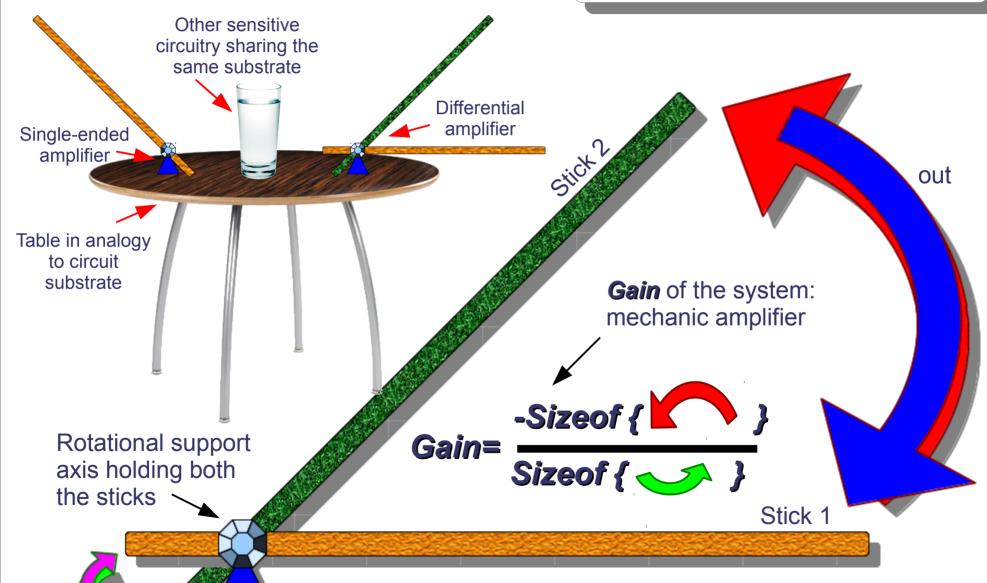




### Differential Amplifier

Generating less noise (also for others) in the cost of more complex design



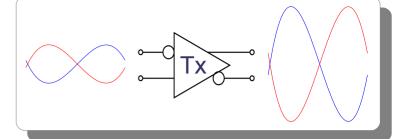


Support

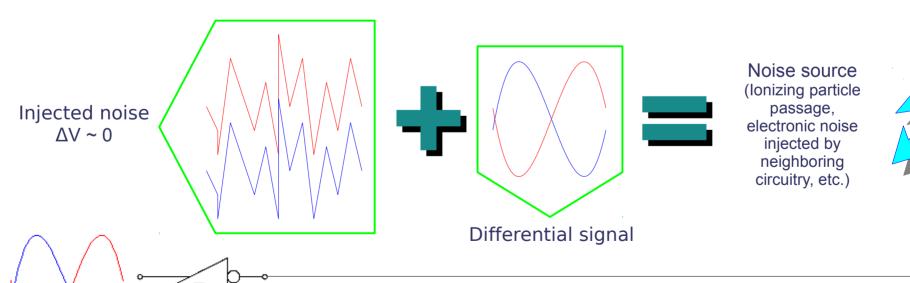
(the amplifier)

### Differential Signaling

Rejecting noise



- The information Tx generates is in the difference
  - Signal creates complementary current images on the substrate
  - Generating less noise for neighboring circuitry
- Rx compares the voltage levels of the pair
- Any noise source should affect both of the lines similarly
  - Generating almost identical transients on both of the wires
  - → Pair wires are close to each other
- Practically high noise rejection is feasible

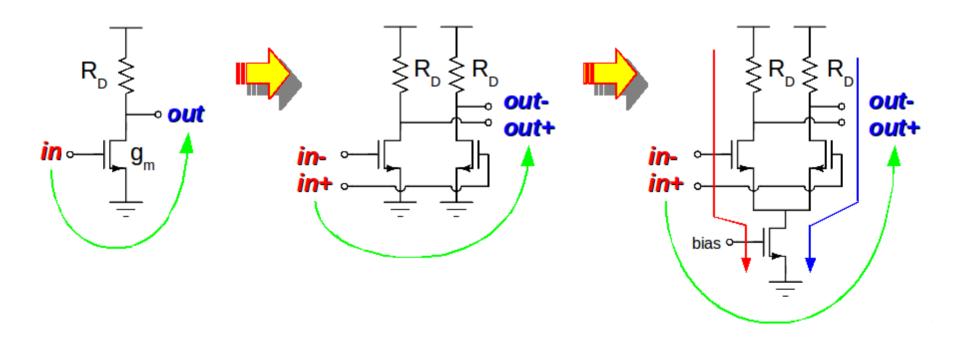




Metal wires

# Differential Signaling Differential gain stage

- Sink current through R<sub>p</sub>
  - → As in increases, out decreases (faster)
- Double the structure to act on both the signals
  - → Drawback: signals can be identical (no differential information)
- Steer the current either through one inverter or the other
  - → Transition at the input changes the path through which the current is steered
  - → Unless metastable, the amplifier has always differential information at he output



# Introduction to the Design of Full-Custom Front-End & Data Transmission ASICs\*

Table of Contents (TOC)

### The Big (but Brief) Picture

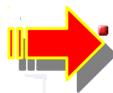
- → Briefly **front-end** FE ASICs
- → Briefly read-out RO systems
- → Briefly serializer SER
- → Briefly phase-lock loop PLL

### Feed-Back Concept

- → A qualitative introduction
- Natural frequency concept ω<sub>n</sub>
- → Real-world examples:
  - **→ Binary** read-out
  - → Time-over threshold
- Adjusting/optimizing loop behavior
  - → Damping ratio §

#### Detector Front-End ASICs

- → Pre-Amplifier: basic idea V<sub>out</sub> / V<sub>in</sub>
- → Transconductance of a transistor g<sub>m</sub>
- Evolving a single-stage amplifier into a real-world application



### **Processing Technology**

- Transistor switch A masterpiece
  - Lithography
  - Formation of an nMOS transistor
- VLSI design flow
  - Parasitic extraction
- Real-world ASIC examples

#### Radiation Tolerance Issues

- Definitions:
  - Single event upset, analog single event transient, latch-up
- Simulating radiation effects on analog circuits

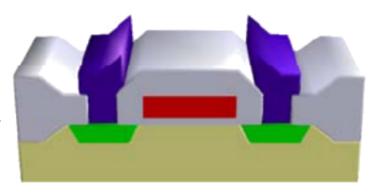
### Potential CMOS Replacements(?)

- Single-layer thick transistors
  - Graphen'ics (benzen lattice)
  - → Molybdenite'ics (MoS<sub>2</sub>)

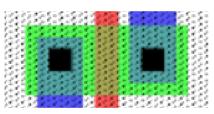
## Semiconductor Switch - Transistor A masterpiece

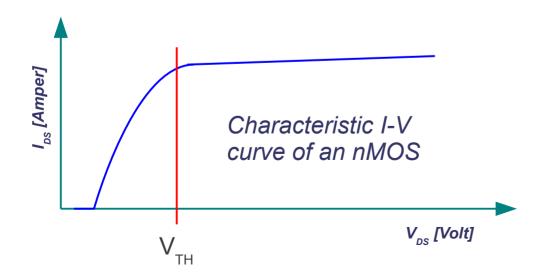
Current conduction between <u>Drain-Source</u>
 as a function of <u>Gate-Source</u> voltage

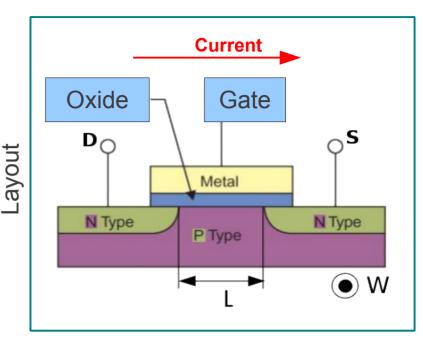
3D view of a single MOS transistor

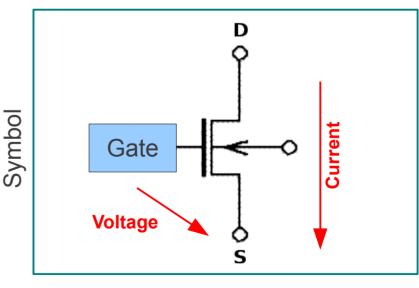


A single MOS transistor as drawn by a designer





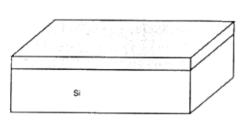




### Lithography

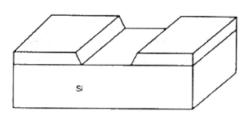
The art of drawing by light

- A real microelectronic circuit is like a very large city composed of many layers
- A specific lithographic mask is needed for each layer to be created
- As an example we will create a "line" on an oxide layer



Initial state



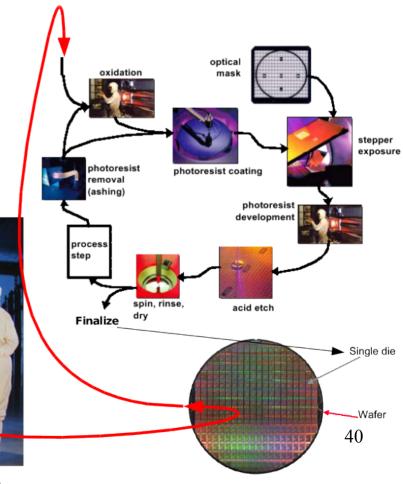


**Target** 

The **ingot** to be sliced into **wafers** 

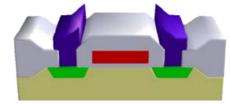


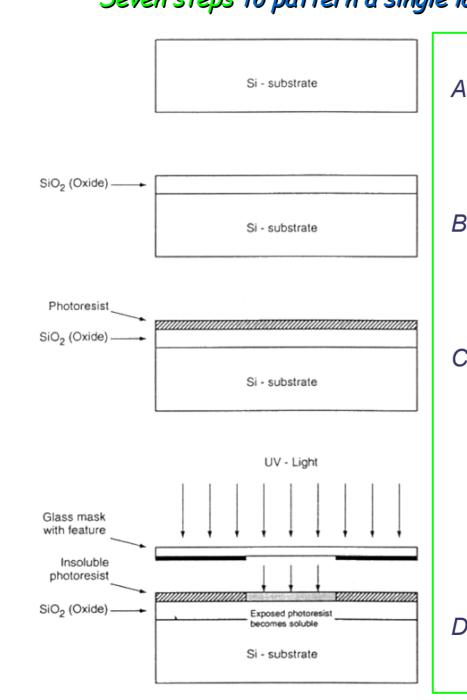


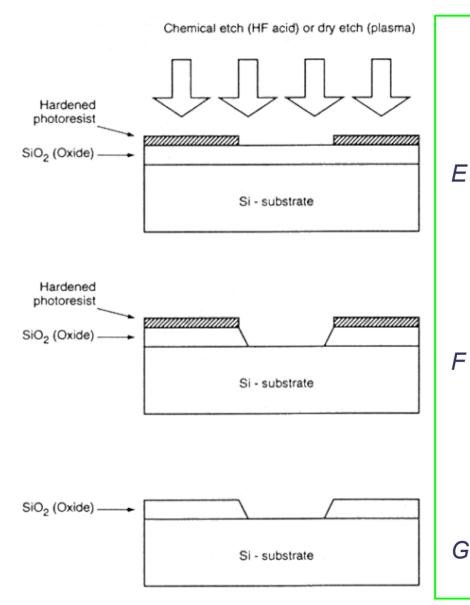


<sup>\*</sup> Please refer to Semiconductor Devices: Physics and Technology by S. M. Sze

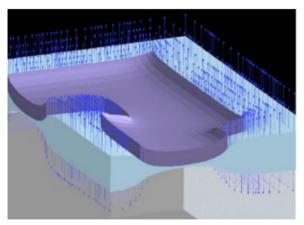
### Just to draw a single line Seven steps to pattern a single layer





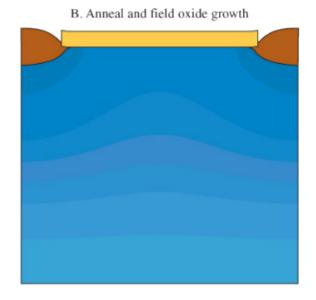


# Fabrication of an nMOS Simplified steps - Part I

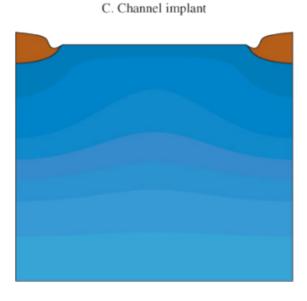


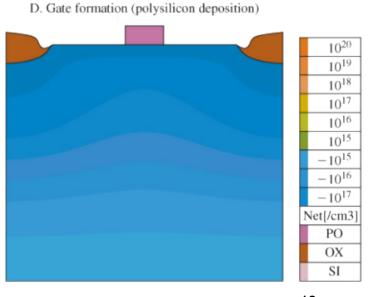


A. Definition of active area



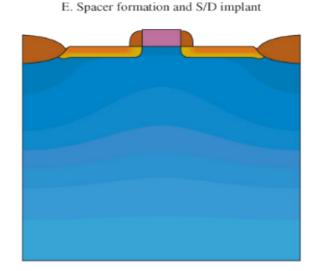
- **Nitride** defines the active areas
- FOX is developed
- Nitride is removed by a solvent
- Polysilicon is deposited

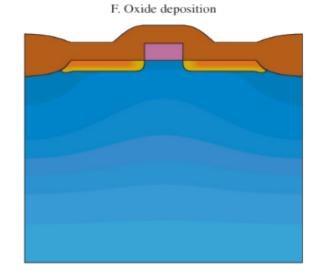


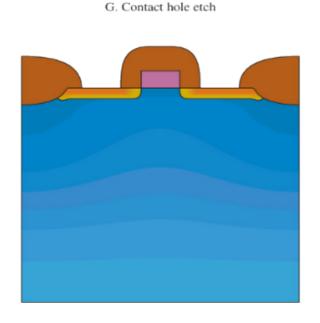


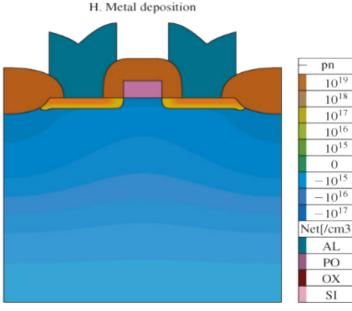
# Fabrication of an nMOS Simplified steps - Part II

- Spacer & active field formation
- Dep. of **SiO**,
- **Etch**ing contact holes
- Metal dep.



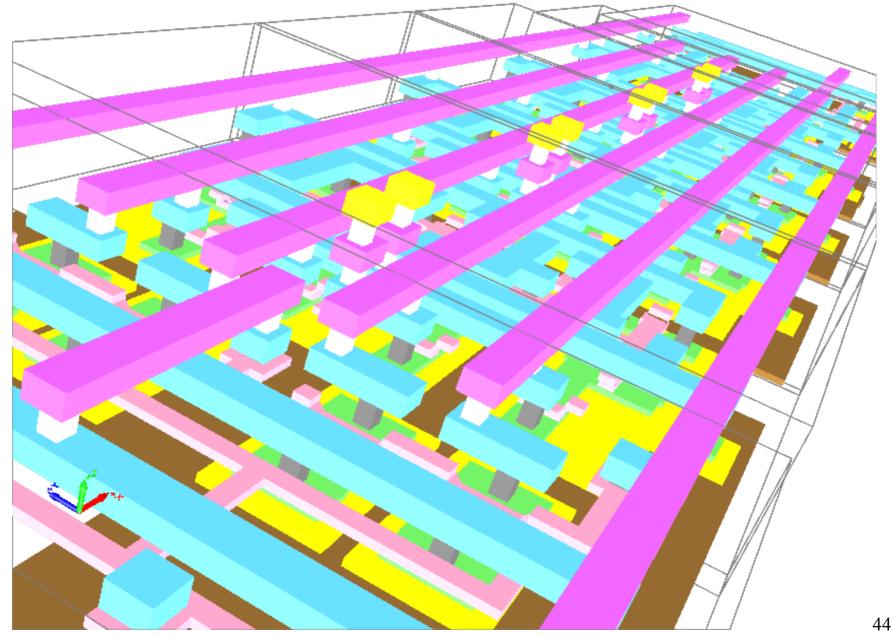






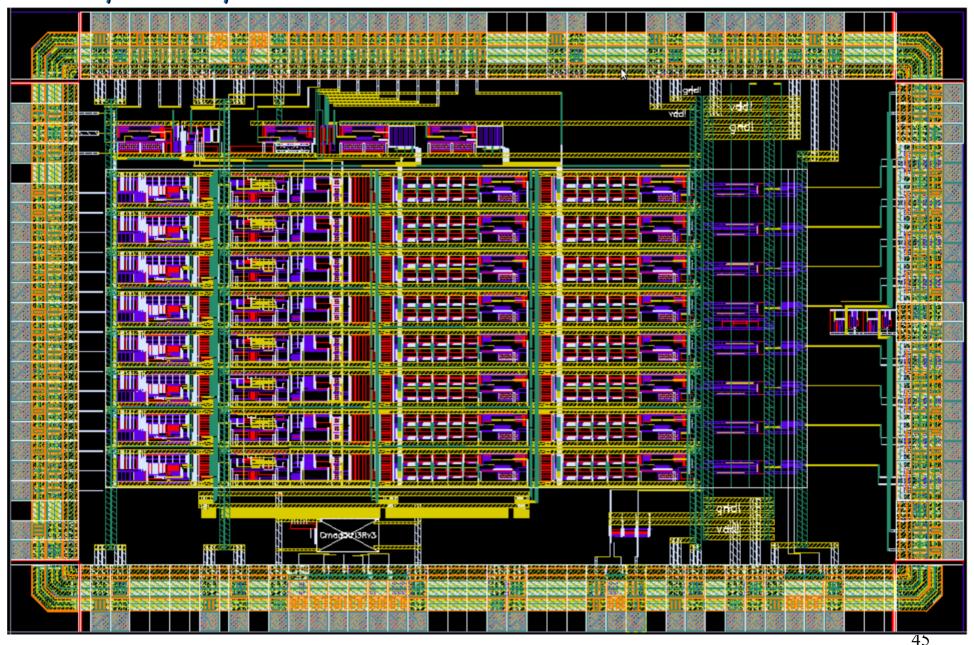
0

# How many layers do you see? A process repeated a few hundred times

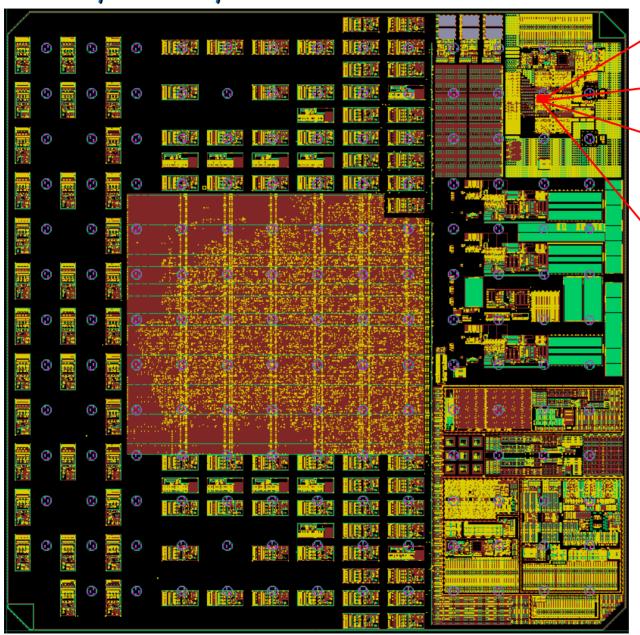


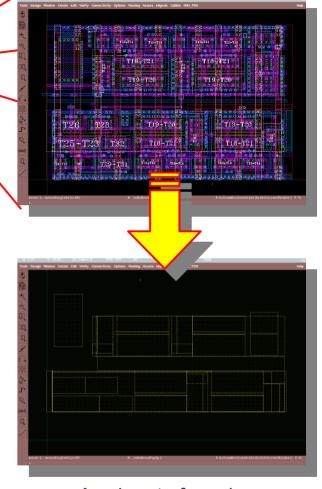
A ring-type oscillator visualized in "electric", an open source CAD tool for ASIC design

# How many layers do you see? A process repeated a few hundred times



# How many layers do you see? A process repeated a few hundred times





A sub-set of masks forming the above block (Animated GIF image)

The first prototype of the SER-DES ASIC for the GBT13 chip-set under development for the Super-LHC at CERN. (130 nm CMOS)

### VLSI Design in Practice

Daily life of an ASIC designer

Interface between process scientist and designer

Focus on reliability and increased manufacturability

T(s) =	$\omega_n^2(\tau s + 1)$
	$\frac{s^2}{N} + 2\xi s \frac{\omega_n}{N} + \frac{\omega_n^2}{N}$

# Seon/120n In-2

D2S Converter

### Layout

**Specifications** 

Schematic entry

Simulation

Design Rule Check

Parasitic Extraction

Layout Versus Schematic check

Post-Layout Simulation

### Contact 5.1 Exact contact size

5.2	Min. poly overlap	1.57
5.3	Min. spacing	2.7
5.4	Min. spacing to gate	2)
6.1	Exact contact size	2)
6.2	Min. active overlap	1.57
6.3	Min. spacing	2 )

6.4 Min. spacing to gate

#### Metal 1

7.1	Min. width	3 λ
7.2.a	Min. spacing	$-3\lambda$
7.3	Min. overlap of any contact	1 λ

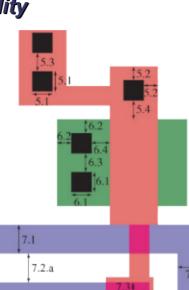
#### Via1

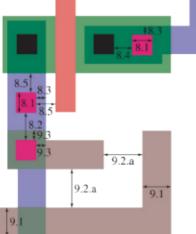
8.1	Exact size	$2\lambda$
8.2	Min. spacing	$3\lambda$
8.3	Min. overlap by metal1	1 λ
8.4	Min. spacing to contact	$2\lambda$
8.5	Min. spac. to poly or act. edge	$2\lambda$

#### Metal2

9.1	Min. width	3 λ
9.2.a	Min. spacing	4 λ
9.3	Min. overlap to via1	1 λ

(\*) Not Drawn

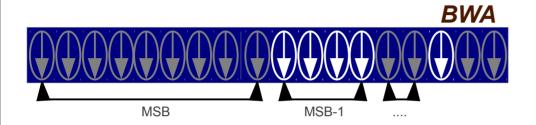


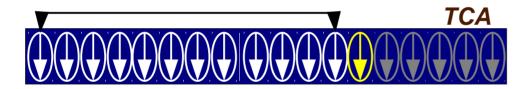


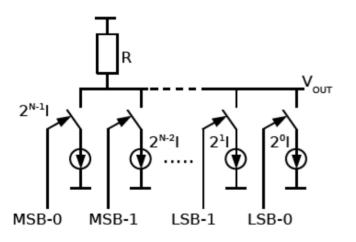
### Architectural Choice

Quantitative comparison between different approaches

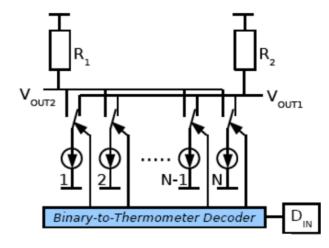
- A 10-Bit current-mode D/A converter
- Two possible architectures; have to choose one
- Need for qualitative comparison: MC is a must



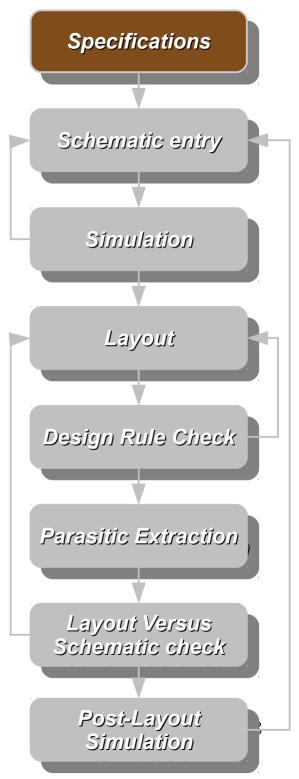




Binary weighted (BWA)

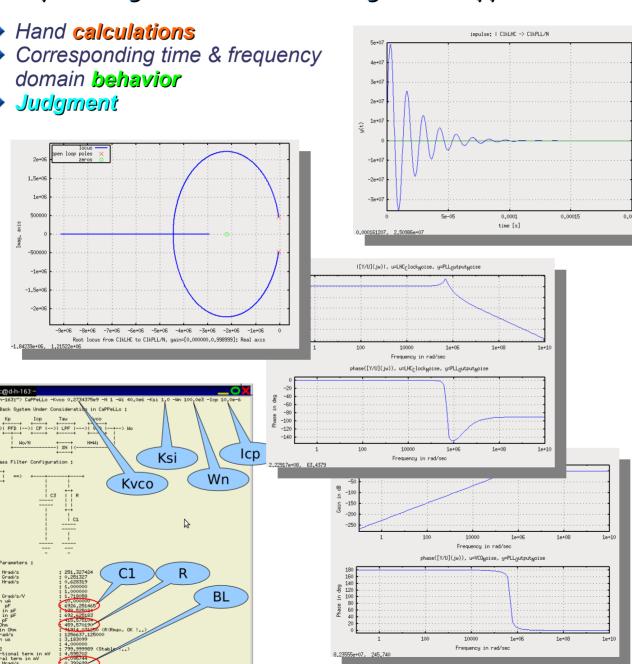


Thermometer coded (TCA)

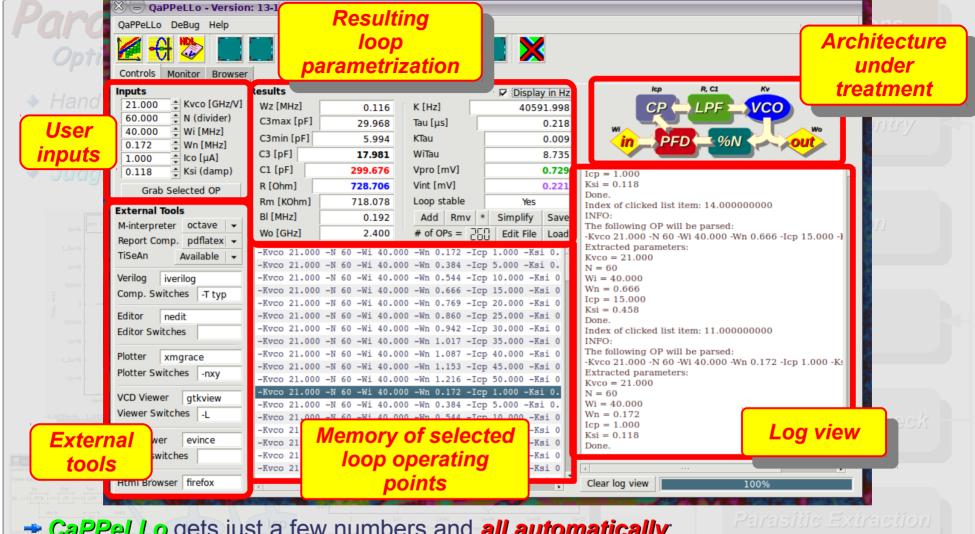


### Parametrization

### Optimizing the choice according to the application



**Specifications** Schematic entry Simulation Layout Design Rule Check Parasitic Extraction Layout Versus Schematic check Post-Layout Simulation



- CaPPeLLo gets just a few numbers and all automatically.
  - Calculates loop parameters and generates the stability map for comparison
  - Calculates frequency domain loop response as
    - Bode and root locus plots, step & impulse responses, noise transfer functions, etc.
  - Generates the verilog model of the architecture with the selected parameters
    - Compiles and runs the verilog model, displays the wave forms
    - Analyzes the jitter data generated during the this simulation
  - Searches for chaos by means of time series analysis and creates attractors, etc.
  - Generates a report summarizing all above actions

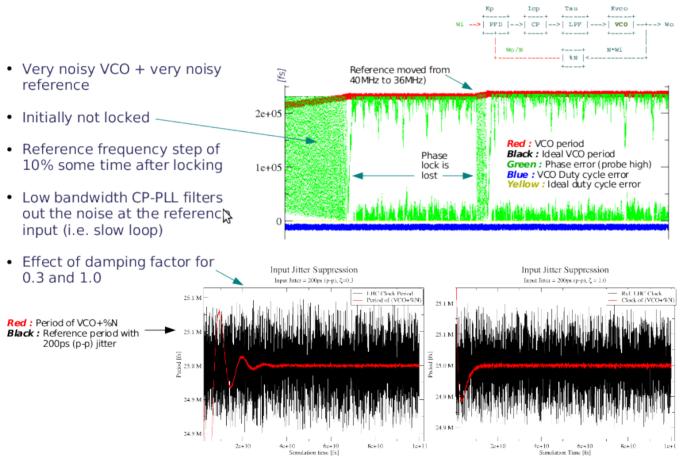
#### Schematic-Level Design Place devices Connect ports Build a hierarchy daTria 🔷 🔀 🔯 d42b-2×7d0 tik Ctr 3 < 7505 tikCtr3 < 7500 reference@nckBrytff ryC&Rock4RW-to **велиения** GENtopF serializer Forth Rosel LEBRUH SERv9\_Faced m Reference/Clock : Periora nos Clos kB **5.0% 180MH** TTC\_bap\_buffer HeCtr0 (464) ttoCty847 odΩutEven≪8248> HcGb147: rvOutOdd<5008> HsCtr2+683 H=05-6 (3-8) ttp:0tr3 < 754: rv9MoCvaleB HeQtr6+7;83 ttoC47<8> rxFilter8ypoin8 Helbert THE ttoOytici: H=059 (48) ttoCtr9 < 0: r-Dood 848 tteCtr t0 < 4:B:

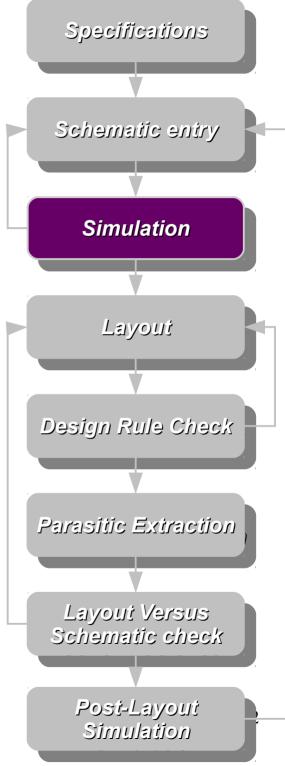
- ⊠——— in Cha

Specifications Schematic entry Simulation Layout Design Rule Check Parasitic Extraction Layout Versus Schematic check Post-Layout Simulation

### Simulation

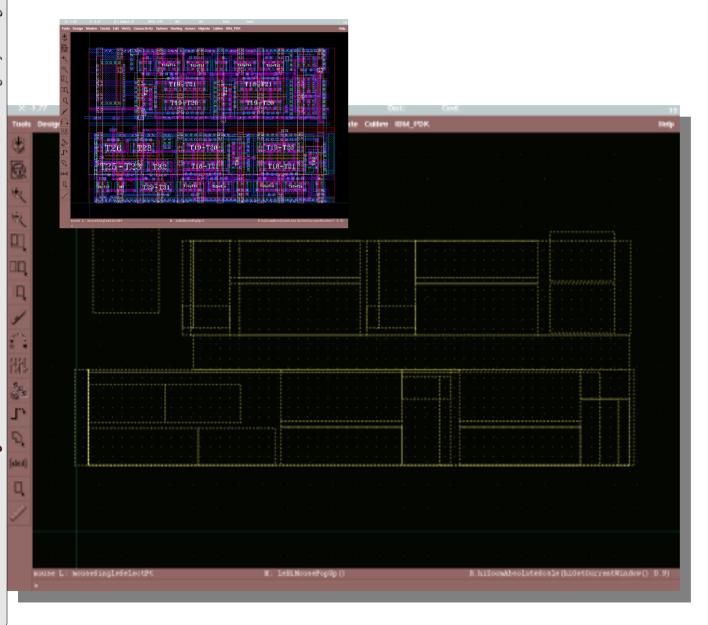
- Model-based time-step simulations (HDLs, MatLab, Octave, Cadence, etc.)
- ◆ Transistor-level SPICE simulations (Spectre, UltraSim, etc.)
- Radiation simulations (Process simulators, Spectre, etc.)

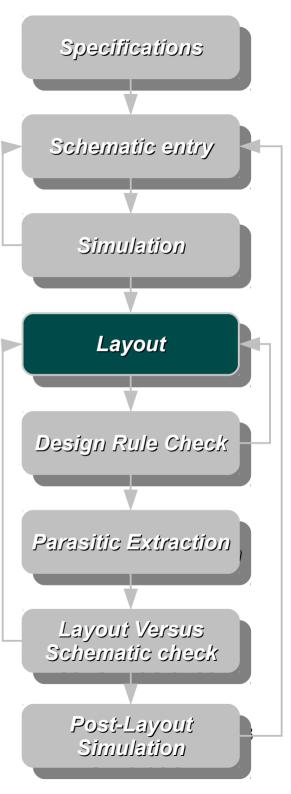




### Layout

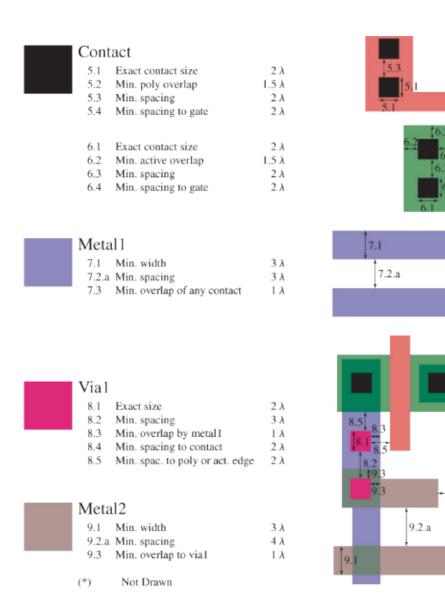
- Lithographic masks are designed
- Actual representation of a circuit on the die



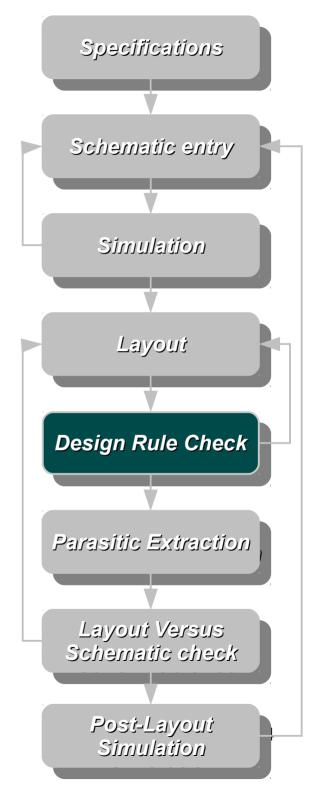




 Infinite different paths of matching what the schematic represents (art)



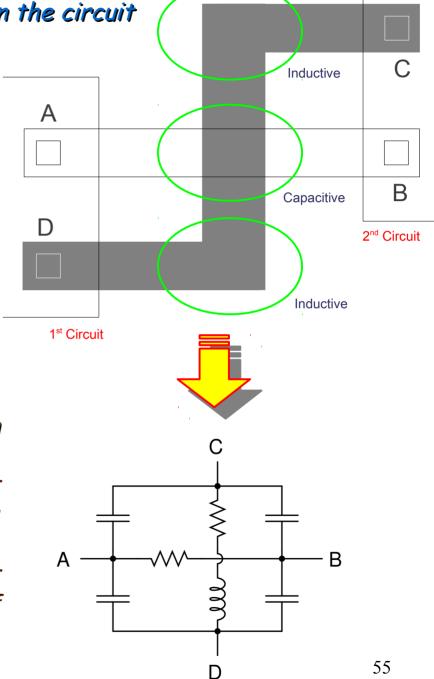
9.1



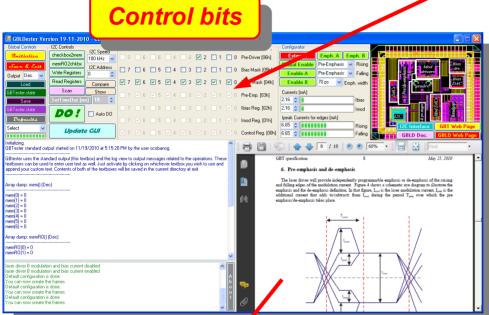
### Parasitic Extraction

For a better physical representation of what is in the circuit

- Perform two simple connections:
  - → Connect the pin A to pin B with metal-1
  - → Connect the pin C to pin D with metal-2
- Designer did not draw any device but the effective circuit has at least the followings:
  - 4 capacitors
  - 2 resistors
  - → 1 inductor
- Things which are not taken into account in schematic are the parasitic devices that can not be avoided but minimized/maximized
  - e.g. minimize input capacitance of a FE or wire capacitances between building blocks
  - → e.g. maximize narrow-band PLL filter capacitance or de-coupling capacitors of any ASIC



### Test Boards and tester/configurator application



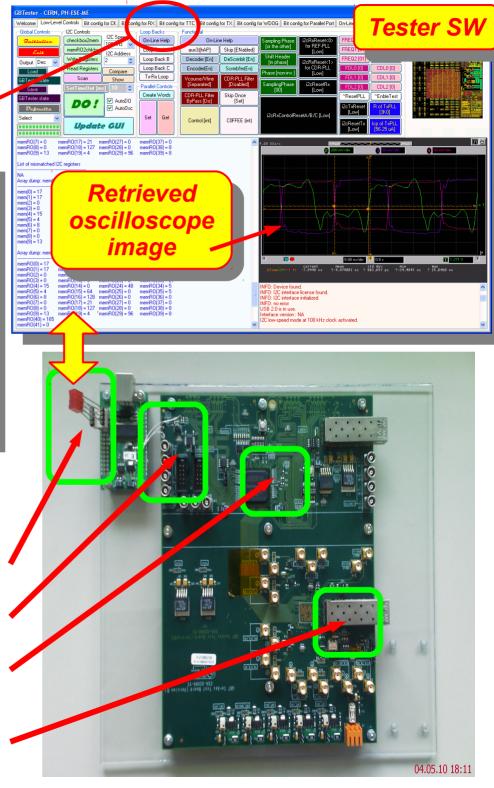
On-line documentation

 $\text{USB} \rightarrow \text{I2C adapter}$ 

I2C & JTAG ports

FPGA (Cyclon-III)

Where the DUT resides (DUT: Device Under Test)



# Introduction to the Design of Full-Custom Front-End & Data Transmission ASICs\*

Table of Contents (TOC)

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- → Pre-Amplifier: basic idea V<sub>out</sub> / V<sub>in</sub>
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- **→ Transistor** switch A masterpiece
  - Lithography
  - Formation of an nMOS transistor
- VLSI design flow
  - Parasitic extraction
- Real-world ASIC examples

### Radiation Tolerance Issues



- Single event upset, analog single event transient, latch-up
- Simulating radiation effects on analog circuits

### Potential CMOS Replacements(?)

- Single-layer thick transistors
  - Graphen'ics (benzen lattice)
  - → Molybdenite'ics (MoS<sub>2</sub>)

### Radiation Issues

### Definitions and failure mechanism

- Single Event Transient (SET)
  - → A transient perturbation on an analog signal due to charge released by an ionizing radiation.
- Single Event Upset (SEU)

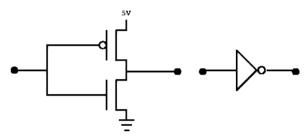
Vdd

BiPolar circuit

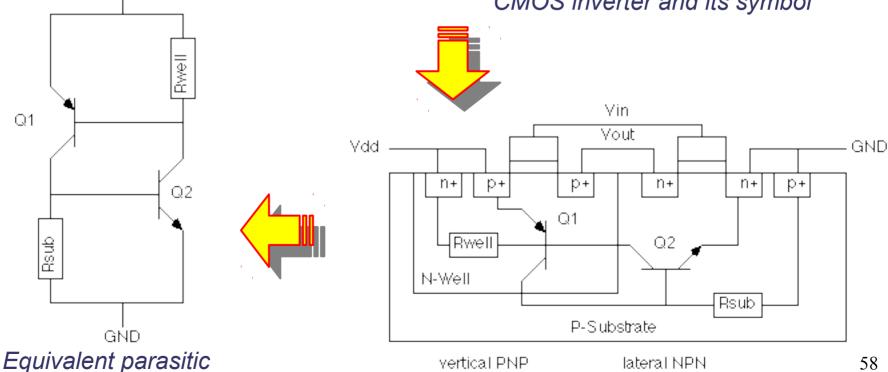
→ State change of a digital circuit due to charge released by an ionizing radiation.

### Latch-Up

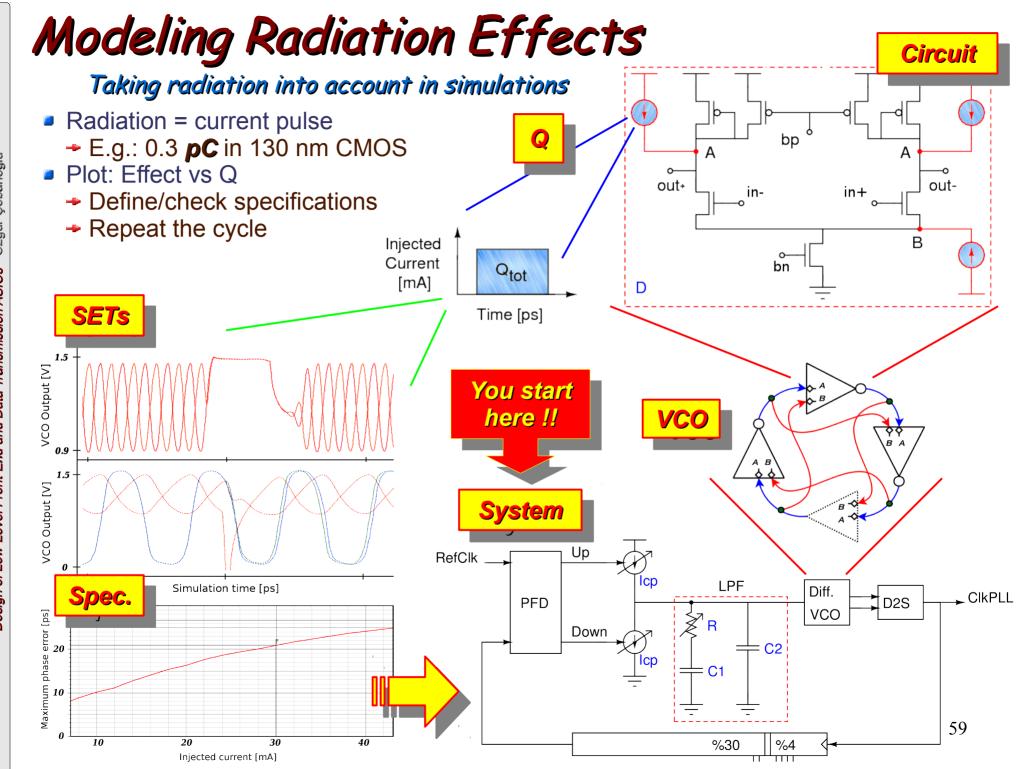
Creation of a low-resistance path between Vdd and Gnd due to a positive feedback loop formed by parasitic devices.



CMOS inverter and its symbol



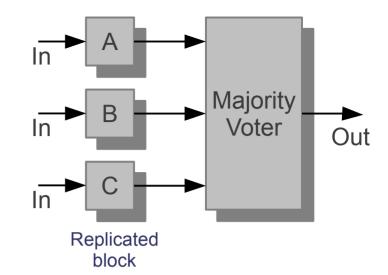
Wafer cross-section of the inverter

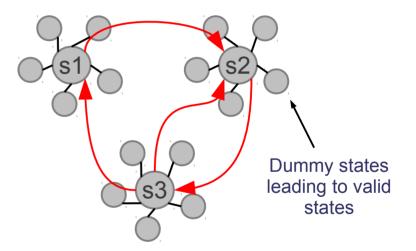


### Rad-Hard Design Tricks

### Adding robustness to circuits

- Use higher current levels and/or larger devices
  - → The current/voltage excursions ionizing particles generate stay insignificant
  - → Prise to pay: increased circuit footprint and power dissipation, slower operation, etc.
- Use triple-well and/or guard-ring structures frequently
  - → To ground any noise before it reaches to sensitive circuitry
- Use Modular Redundancy (nMR)
  - → Replicate circuitry and vote at the output, Triple Modular Redundancy (TMR) is commonly used
  - → The probability for an ionizing particle to affect all the three blocks at the same time is very low, therefore this technique is commonly used to harden designs against SEU





- Use dummy states to protect Finite State Machines (FSM) against SEUs
  - → If a state change occurs due to an ionizing particle passage, the FSM can return to a valid state without impairing
  - → Prise to pay: more complex FSM design, increased power dissipation and circuit footprint
- Place the ASICs within magnet shadows (where applicable)
  - → To decrease radiation tolerance requirements

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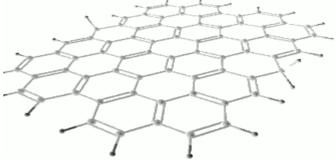
- Single-layer thick transistors
  - Graphen'ics (benzen lattice)
  - Molybdenite'ics (MoS<sub>2</sub>)



### Potential CMOS Replacements(?)

Next Generation Single Atom- or Molecule-Thick Revolutionary Technologies

- Single-atom thick flat carbon (C) network: Graphene
  - Brought 2010 Nobel prize
  - Graphene-based devices including transistors are being constructed by many groups



Top-gate
Source
Drain
SiO<sub>2</sub>
Si substrate

Back-gate

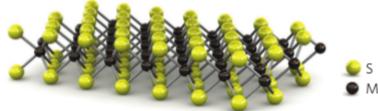
First Observed in 1969: PLATINUM SURFACE LEED RINGS, SURFACE SCIENCE 17 267-270

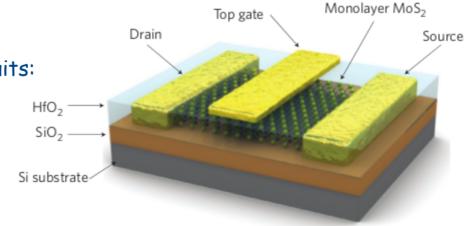
Nobel Prized Study in 2004: Electric Field Effect in Atomically Thin Carbon Films, K. S. Novoselov, 1 A. K. Geim, S. V. Morozov, D. Jiang, Y. Zhang, S. V. Dubonos, I. V. Grigorieva, A. A. Firsov

Device seen on the right: http://www.nature.com/nnano/journal/v5/n7/full/nnano.2010.89.html

- → Single-molecule thick molybdenite (MoS₂) network
  - Intrinsically semi-conductor
  - Recently characterized
  - Demonstrated to be suitable for **n-type** circuits:

http://www.nature.com/nnano/journal/v6/n3/full/nnano.2010.279.html





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  - → Damping ratio §

#### Detector Front-End ASICs

- → Pre-Amplifier: basic idea V<sub>out</sub> / V<sub>in</sub>
- → Transconductance of a transistor g<sub>m</sub>
- Evolving a single-stage amplifier into a real-world application

### Processing Technology

- → Transistor switch A masterpiece
  - → Lithography
  - Formation of an nMOS transistor
- VLSI design flow
  - Parasitic extraction
- Real-world ASIC examples

#### Radiation Tolerance Issues

- Definitions:
  - Single event upset, analog single event transient, latch-up
- Simulating radiation effects on analog circuits

### Potential CMOS Replacements(?)

- Single-layer thick transistors
  - Graphen'ics (benzen lattice)
  - → Molybdenite'ics (MoS<sub>2</sub>)